| ASSOCIATION CONNECTING<br>ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES®<br>international and Par | PC. Bannock     | burn, Illinois, A          | ll rights reserved utions. | under both              | This docum<br>level parts, t   | ent is a declaration entite declaration entite | on of the su                                | ibstances v<br>s all lower | vithin the manufactule level materials for v | urer listed which the | item. Note:<br>manufactur       | if the item is an as<br>er has engineering | sembly with low responsibility. |  |
|--|-----------------|----------------------------|----------------------------|-------------------------|--|--|---|----------------------------|--|-----------------------|---------------------------------|--|---------------------------------|--|
|  |                 |                            |                            | Form Type<br>Distribute | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials and Mf |  |   |                            |  | Ifg Informa           | ation                           |  |                                 |  |
| Supplier Information   |                 |                            |                            |                         |  |  |   |                            |  |                       |                                 |  |                                 |  |
| Company name*  | Company uni     | Company unique ID          |                            |                         | Unique ID Authority  |  |   |                            | Respon                                       | Response Date*        |                                 |  |                                 |  |
| onsemi   |                 |                            |                            |                         |  |  |   |                            |  | 2025-0                | 2025-05-25                      |  |                                 |  |
| Contact Name Title - Contact   |                 |                            |                            |                         |  | Phone - Contact*                               |   |                            |  | Email ·               | Email - Contact*                |  |                                 |  |
| Product-Env-Stewards Product En  |                 |                            | Enviro Compliance          |                         |  | NA   |   |                            |  | Produ                 | Product-Env-Stewards@onsemi.com |  |                                 |  |
| Authorized Representative* Title - Representative  |                 |                            | entative                   |                         | Phone - Representative*  |  |   | Email ·                    | Email - Representative*                      |                       |                                 |  |                                 |  |
| Product-Env-Stewards Pro   |                 |                            | Product Enviro Compliance  |                         |  | NA   |   |                            |  | Produ                 | Product-Env-Stewards@onsemi.com |  |                                 |  |
| Requester Item Number  | Mfr Item Number |                            | Imber Mfr Item Name        |                         |  | Effective Date                                 | ve Date Version Manufacturing Site          |                            |  | Weight*               | UOM                             | Unit Type                                  |                                 |  |
|  | NLV74<br>G      | LV74VHC4051DR2 ANALOG MULT |                            | TIPLEXERS/DE            | RS/DEMUL 2025-0  |  |   | PI                         | PH1  |                       | 142.68                          | mg   | Each                            |  |
| Ianufacturing Proccess Informa   | tion            |                            |                            |                         |  |  |   |                            |  |                       |                                 |  |                                 |  |
| Terminal Plating / Grid Array M  | aterial         | al Terminal Base Alloy     |                            | J-STD-020 MSL           | SL Rating Peak   |  | k Process Body Temperature Max Time at Peal |                            | k Tempera                                    | ture Num              | nber of Reflow Cyc              | les  |                                 |  |
| Matte Tin (Sn) - annealed CU A   |                 | CU Alloy                   | 1                          |                         |  | <b>260</b> C                                   |   | С                          | 30 seco                                      |                       | seconds 3                       |  |                                 |  |
| omments  |                 |                            |                            |                         |  |  |   |                            |  |                       |                                 |  |                                 |  |
| vel 1 - maximum time at peak temperat  | ure during so   | oldering is 10-3           | 0 seconds                  |                         |  |  |   |                            |  |                       |                                 |  |                                 |  |
| or more information regarding material   | composition     | please refer to            | page 3                     |                         |  |  |   |                            |  |                       |                                 |  |                                 |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| select a ROHS exemption, if appli<br>sigma range of distribution unless | otherwise noted). | it of the substance of the Pl | PM concentration | [F] Optionally enter the positive (+) and n | legative (-) tolerance in per | cent (Note: percer | it tolerance values are | expected to cover a 3 |
|---|-------------------|-------------------------------|------------------|---|-------------------------------|--------------------|-------------------------|-----------------------|
| Homogeneous Material  | Weight            | Unit of Measure               | Level            | Substance                                   | CAS                           | Exempt             | Weight                  | Unit of Measure       |
| Die   | 2.73              | mg                            | Supplier         | Silicon (Si)                                | 7440-21-3                     |                    | 2.73                    | mg                    |
| Die Attach  | 4.85              | mg                            | Supplier         | Silver (Ag)                                 | 7440-22-4                     |                    | 3.6375                  | mg                    |
|   |                   |                               | Supplier         | Epoxy resins                                | 129915-35-1                   |                    | 1.2125                  | mg                    |
| Lead Frame  | 75.92             | mg                            | Supplier         | Silver (Ag)                                 | 7440-22-4                     |                    | 0.7592                  | mg                    |
|   |                   |                               | Supplier         | Zinc (Zn)                                   | 7440-66-6                     |                    | 0.1518                  | mg                    |
|   |                   |                               | Supplier         | Iron (Fe)                                   | 7439-89-6                     |                    | 1.9739                  | mg                    |
|   |                   |                               | Supplier         | Copper (Cu)                                 | 7440-50-8                     |                    | 73.035                  | mg                    |
| Mold Compound-Black   | 55.11             | mg                            |                  | Epoxy resin                                 | proprietary data              |                    | 2.7555                  | mg                    |
|   |                   |                               | Supplier         | Phenolic Resin                              | Proprietary Data              |                    | 2.7555                  | mg                    |
|   |                   |                               | Supplier         | Ortho Cresol Novolac Resin                  | 29690-82-2                    |                    | 1.1022                  | mg                    |
|   |                   |                               | Supplier         | Carbon Black (C)                            | 1333-86-4                     |                    | 0.2756                  | mg                    |
|   |                   |                               | Supplier         | Fused Silica (SiO2)                         | 60676-86-0                    |                    | 48.2213                 | mg                    |
| Plating   | 3.73              | mg                            | Supplier         | Tin (Sn)                                    | 7440-31-5                     |                    | 3.73                    | mg                    |
| Wire Bond - Cu  | 0.34              | mg                            | Supplier         | Copper (Cu)                                 | 7440-50-8                     |                    | 0.34                    | mg                    |